

A960D+V3 Motherboard



- Socket AM3+
- Supports AMD FX Series/Phenom II Series/Athlon II Series /Sempron Series Processors
- Hyper Transport Technology up to 5.2G
- Support 2-DIMM DDR3-1866(OC)/ up to 16G maximum capacity
- Supports AMD Cool'n'Quiet Technology

Specifcation	
CPU SUPPORT	AMD FX™ 處理器 AMD Phenom™ II X6 處理器 AMD Phenom™ II X4 處理器 AMD Phenom™ II X3 處理器 AMD Phenom™ II X2 處理器 AMD Athlon™ II X4 處理器 AMD Athlon™ II X3 處理器 AMD Athlon™ II X3 處理器 AMD Sempron™ 處理器 AMD Sempron™ 處理器 Maximum CPU TDP (最大散熱功率): 125Watt
HT	Support HT3.0 up to 5.2GT/s (Depends on AMD CPU Specification)
MEMORY	支援雙通道 DDR3 800/1066/1333/1600(OC)/1866(OC) MHz 2 x DDR3 DIMM插槽,支援最高容量為16GB *DDR3-1866 僅限於 AM3+ CPU
INTEGRATED VIDEO	ATI Radeon™ HD3000 Graphics, On Board Graphic Max. Memory Share Up to 1024 MB
STORAGE	4 x SATA II 接頭 (3Gb/s) 1 x IDE Connector 支援 SATA RAID: 0,1,10
LAN	Realtek RTL8111H 10/100/1000Mb/s 半/全雙功能,自動協商模式
AUDIO CODEC	Realtek ALC662 5.1 聲道,支援高解析音效輸出
USB	8 x USB 2.0 連接埠(後側面板4個連接埠,內建接頭支援4個連接埠)
EXPANSION SLOT	1 x PCle 2.0 x16 插槽 1 x PCle 2.0 x1 插槽 1 x PCl 插槽

REAR I/O	1 x PS/2 滑鼠連接埠 1 x PS/2 鍵盤連接埠 4 x USB 2.0 連接埠 1 x DVI 連接埠 1 x VGA 連接埠 1 x LAN 連接埠 3 x 音效連接埠
INTERNAL I/O	2 x USB 2.0 連接埠 4 x SATA II 接頭(3Gb/s) 1 x IDE 接頭 1 x 前置音效接頭
INTERIOR I	1 x 前置面板接頭 1 x CPU 風扇接頭 1 x 系统風扇接頭 1 x 印表機接頭
H/W MONITORING	CPU / System Temperature Monitoring CPU / System Fan Monitoring Smart / Manual CPU Fan Control System Voltage Monitoring
DIMENSION	Micro ATX Form Factor Dimension: 23.5cm x 19cm (W x L)
OS SUPPORT	Supports Windows XP / Vista / 7 / 8 / 8.1 / 10 *如有增加或減少任何OS支援, Biostar保留不預先通知的權利。
BUNDLE SOFTWARE	BullGuard BIO-Remote2 Smart Speed LAN
ACCESSORIES	2 x SATA Cable 1 x I/O Shield 1 x DVD Driver 1 x Quick Guide
FEATURES	Supports Solid capacitor BIO-FLASHER Supports Charger Booster Supports BIOS Online Update

OVERVIEW



AM3/AM2+ Support

Supporting upcoming AMD Socket AM3/AM2+ 45nm processors, it delivers better overclocking capabilities and reduces power consumption. Moreover, AM3 CPU supports both DDR2 /DDR3 memory module and accelerates data transfer rate by up to 5200MT/s via HyperTransport 3.0 technology.



HD Audio

Provides high quality sound with minimal loss of audio fidelity.



DVI

DVI is better than VGA for LCD displays since it is digital while VGA is analog. For LCD displays, the picture is digitized pixel per pixel. Through DVI, the panel gets data for each pixel, so the picture generated in the Graphics device matches the pixels on the panel itself.





The popularity of PC usage and working environment is getting deteriorating and moist (rural, coastal, etc.). The PCB will be oxidizing easily by damp or absorbed moisture, and ionic migration or CAF (Conductive Anodic Filament) will be generated. Moisture-proof PCB meets high density and high reliability requirements for moisture proof.



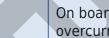
Low RdsOn P-Pak MOS

Low resistance design can significantly reduce the current out of energy loss. Low temperature, small size, excellent thermal conductivity.



ESD Protection

ESD (Electrostatic Discharge) is the major factor to destroy the PC by electrical overstress (EOS) condition. ESD occurred by PC users when touch any devices connect to a PC, which may result in damage to the motherboard or parts. ESD protection is designed to protect the motherboard and equipment from damage by EOS.



USB Polyswitch

On board dedicated power fuse to help prevent USB port failure. It prevents USB Port overcurrent and safe guard your system and device lifespan.



13/4



OC / OV / OH Protection

OC / OV / OH Protection design detects overvoltage conditions and prevents voltage surges from spreading in real time. It also actively cuts off the overvoltage supply to protect your system.

*The specification and pictures are subject to change without notice and the package contents may differ by area or your motherboard version!



